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Global IC Package Heat Spreaders Supply, Demand and Key Producers, 2026-2032

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Abstracts

The global IC Package Heat Spreaders market size is expected to reach $ 2188 million by 2032, rising at a market growth of 12.1% CAGR during the forecast period (2026-2032).

A heat spreader is high thermal conductive metallic materials for efficient heat dissipation from an IC chip in a semiconductor package.

This report studies the Heat Spreaders for semiconductor IC package, include FC (Flip Chip) heat spreaders and BGA heat spreaders. The Flip Chip heat spreaders include Lid/Ring type, Hat type, Flat Top type and Cavity type heat spreaders, etc. These spreaders are used in CPU packages for personal computers, CPU packages for servers, SoC/FPGA packages for automotive devices, Processor packages for communication equipment, and AI processor packages, etc.

Heat spreaders are one of the fundamental heat dissipation components used in various industries. They are typically made of high thermal conductivity metals such as copper or aluminum. In the electronics industry, heat spreaders or heat sinks are installed on electronic components or chips to transfer or dissipate the heat generated by the components using the thermal conductivity of the heat dissipation material itself. Heat spreaders find wide applications in the electronic information industry, semiconductor industry, and optoelectronic component industry, with downstream applications extending to the 3C industry.

Furthermore, electric vehicles (EVs) and hybrid electric vehicles (HEVs) have become a major trend in automotive development. In the inverters and rectifiers of electric vehicles, high-power chip modules pose thermal dissipation challenges. Currently, the

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mainstream solution for such designs is to use water-cooled heat spreaders. By utilizing highly thermally conductive metal materials, along with metal processing techniques and surface treatments, the chip temperature can be controlled within an acceptable range using water cooling. The thermal design of water-cooled heat spreaders needs to effectively dissipate the heat generated by the chips, while considering the cost and manufacturability aspects of the design for mass production.

IC Package Heat Spreaders can be segmented by material, size, geometry and surface treatment. Under the report's material classification, Copper Heat Spreaders and Stainless Steel Heat Spreaders are the two principal categories. Copper remains the mainstream thermal material because of its high thermal conductivity; SHINKO, for example, specifies C1020 and C1100 copper, with electrolytic Ni or Ni plus selective Au plating, and supports outer dimensions of approximately 10–100 mm and thicknesses of 1.0–4.5 mm. According to the report model, copper represented 79.94% of global heat-spreader revenue in 2025, versus 20.06% for stainless steel, while the shares are forecast to shift to 55.60% and 44.40%, respectively, by 2032. By size, products are divided into Large Size products of 35×35 mm and above and Small Size products below 35×35 mm; Large Size accounted for 54.65% of revenue in 2025 and is projected to reach 72.34% in 2032. Product geometries are simultaneously evolving from conventional flat lids toward cavity, multi-step, pedestal, ring and heterogeneous-integration structures, while manufacturing increasingly combines precision stamping, machining, forging, flattening and advanced surface treatment.

Global IC Package Heat Spreader demand is undergoing a fundamental transition from PC-oriented demand toward server, data-center and AI-chip packaging. According to the report model, PC CPU/GPU applications accounted for 67.68% of global revenue in 2021, compared with only 19.42% for Server/Data Center/AI Chip Packages. By 2025, the respective shares had converged to 46.22% and 44.22%, while in 2026E the Server/Data Center/AI Chip Package segment is estimated to rise sharply to 57.92%, compared with 34.58% for PC CPU/GPU. By 2032, the server/data-center/AI segment is forecast to reach 75.72% of global revenue. This transition is consistent with downstream fundamentals: TrendForce raised its 2026 AI-server shipment growth forecast to nearly 31% YoY, supported by strong investment in GPU clusters, proprietary AI ASICs and AI data-center infrastructure. Automotive SoC/FPGA remains smaller but structurally attractive because of ADAS, centralized computing and software-defined vehicles, while game consoles and conventional consumer applications are expected to account for a declining proportion of industry revenue.

The global IC Package Heat Spreaders market is highly concentrated, with competition

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increasingly centered on large-size precision processing, advanced customer qualification, vertical manufacturing integration and exposure to AI/HPC packages. Based on the report's 2025 revenue estimates, Jentech Precision Industrial ranked first with a 51.58% global share, followed by Solstice Advanced Materials at 20.09%, SHINKO at 11.77% and I-Chiun at 6.86%, implying a combined CR4 of approximately 90.3%. Jentech's share increased from 30.27% in 2021 to more than 50% in 2024–2025, reflecting strong positioning in high-value CPU/GPU and AI/server heat spreaders. Solstice continues to include heat spreaders and thermal interface materials in its Electronic Materials portfolio and identifies CPU/GPU cooling and advanced packaging as key high-value applications. SHINKO retains integrated capabilities covering tooling, transfer stamping, machining and surface treatment. Meanwhile, Taiwan suppliers such as I-Chiun, Favor Precision and Niching benefit from proximity to the world's leading advanced-packaging ecosystem, while Chinese suppliers including Shandong Ruisi, HongRiDa and Ningbo S J are increasingly entering domestic CPU/GPU and AI-chip supply chains.

The industry is transitioning from a mature PC-oriented precision-metal component market into a higher-value semiconductor thermal-management segment closely linked to advanced packaging. Three structural changes are particularly evident. First, the product mix is rapidly shifting toward large-size heat spreaders: products of 35×35 mm and above increased from 36.41% of global revenue in 2021 to 54.65% in 2025 and are estimated at 61.47% in 2026E. Second, the application mix is rapidly shifting toward server/data-center/AI-chip packages, whose revenue share is estimated to rise from 19.42% in 2021 to 57.92% in 2026E. Third, production value is becoming increasingly concentrated in Taiwan: according to the report model, Taiwan's global production-value share increased from 43.03% in 2021 to 64.14% in 2025 and is estimated at 67.33% in 2026E. This is closely related to Taiwan's concentration of heat-spreader suppliers and advanced AI/HPC packaging capacity. TSMC states that 3.5-reticle-size CoWoS-L has been in production since 2024, 5.5-reticle-size CoWoS-L is scheduled to complete qualification in 2026, and development of a 9.5-reticle-size version is progressing.

The medium- to long-term growth of IC Package Heat Spreaders will be driven primarily by AI/HPC computing growth, advanced-package enlargement, increasing chip power density, heterogeneous integration, larger IHS dimensions and tighter thermal-mechanical specifications. AI GPUs and proprietary AI ASICs increasingly integrate multiple logic chiplets and HBM stacks, expanding package area and power consumption while increasing localized heat flux. This directly drives demand for larger, thicker and more structurally complex IHS products with tighter flatness, residual-stress

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and plating control. TSMC's roadmap toward 5.5-reticle and even 9.5-reticle CoWoS-L packages provides clear evidence of continued package enlargement. On the demand side, TrendForce's latest forecast of nearly 31% AI-server shipment growth in 2026 and continued expansion of hyperscaler AI infrastructure provide a strong structural catalyst. On the supply side, manufacturers are moving toward vertically integrated processing that combines precision stamping, forging, CNC machining, flattening/CMP, precision cleaning and advanced plating. As a result, future industry growth will increasingly come not only from higher unit shipments, but also from the rising revenue contribution of server/data-center/AI-chip packages, large-size products, more demanding materials and higher-value manufacturing processes.

Report Scope

This report studies the global IC Package Heat Spreaders production, demand, key manufacturers, and key regions.

This report is a detailed and comprehensive analysis of the world market for IC Package Heat Spreaders and provides market size (US$ million) and Year-over-Year (YoY) Growth, considering 2025 as the base year. This report explores demand trends and competition, as well as details the characteristics of IC Package Heat Spreaders that contribute to its increasing demand across many markets.

Highlights and key features of the study

Global IC Package Heat Spreaders total production and demand, 2021-2032, (Million Pcs)

Global IC Package Heat Spreaders total production value, 2021-2032, (USD Million)

Global IC Package Heat Spreaders production by region & country, production, value, CAGR, 2021-2032, (USD Million) & (Million Pcs), (based on production site)

Global IC Package Heat Spreaders consumption by region & country, CAGR, 2021-2032 & (Million Pcs)

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U.S. VS China: IC Package Heat Spreaders domestic production, consumption, key domestic manufacturers and share

Global IC Package Heat Spreaders production by manufacturer, production, price, value and market share 2021-2026, (USD Million) & (Million Pcs)

Global IC Package Heat Spreaders production by Material, production, value, CAGR, 2021-2032, (USD Million) & (Million Pcs)

Global IC Package Heat Spreaders production by Application, production, value, CAGR, 2021-2032, (USD Million) & (Million Pcs)

This report profiles key players in the global IC Package Heat Spreaders market based on the following parameters - company overview, production, value, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include Shinko, Honeywell Advanced Materials, Jentech Precision Industrial, I-Chiun, Favor Precision Technology, Niching Industrial Corporation, Fastrong Technologies Corp., ECE (Excel Cell Electronic), Shandong Ruisi Precision Industry, HongRiDa Electronics (HRD), etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Stakeholders would have ease in decision-making through various strategy matrices used in analyzing the World IC Package Heat Spreaders market

Detailed Segmentation:

Each section contains quantitative market data including market by value (US$ Millions), volume (production, consumption) & (Million Pcs) and average price (US$/Pcs) by manufacturer, by Material, and by Application. Data is given for the years 2021-2032 by year with 2025 as the base year, 2026 as the estimate year, and 2027-2032 as the forecast year.

Global IC Package Heat Spreaders Market, By Region:

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United States

China

Europe

Japan

South Korea

ASEAN

India

Rest of World

Market Segmentation

Global IC Package Heat Spreaders Market, Segmentation by Material:

Cu Heat Spreader

Stainless Steel Heat Spreader

Global IC Package Heat Spreaders Market, Segmentation by Size:

Large Size (35*35mm and Above)

Small Size (35*35mm Below)

Global IC Package Heat Spreaders Market, Segmentation by Type:

Flip Chip Heat Spreader

BGA Heat Spreader

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Global IC Package Heat Spreaders Market, Segmentation by Application:

PC CPU/GPU Package

Server/Data Center/AI Chip Package

Automotive SoC/FPGA Package

Gaming Console

Others

Companies Profiled:

Shinko

Honeywell Advanced Materials

Jentech Precision Industrial

I-Chiun

Favor Precision Technology

Niching Industrial Corporation

Fastrong Technologies Corp.

ECE (Excel Cell Electronic)

Shandong Ruisi Precision Industry

HongRiDa Electronics (HRD)

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TBT Co., Ltd

Ningbo S J Electronics

Key Questions Answered

1. How big is the global IC Package Heat Spreaders market?
2. What is the demand of the global IC Package Heat Spreaders market?
3. What is the year over year growth of the global IC Package Heat Spreaders market?
4. What is the total value of the global IC Package Heat Spreaders market?
5. Who are the Major Players in the global IC Package Heat Spreaders market?
6. What are the growth factors driving the market demand?

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Contents

1 SUPPLY SUMMARY

1.1 IC Package Heat Spreaders Introduction
1.2 World IC Package Heat Spreaders Supply & Forecast
  1.2.1 World IC Package Heat Spreaders Production Value (2021 & 2025 & 2032)
  1.2.2 World IC Package Heat Spreaders Production (2021-2032)
  1.2.3 World IC Package Heat Spreaders Pricing Trends (2021-2032)
1.3 World IC Package Heat Spreaders Production by Region (Based on Production Site)
  1.3.1 World IC Package Heat Spreaders Production Value by Region (2021-2032)
  1.3.2 World IC Package Heat Spreaders Production by Region (2021-2032)
  1.3.3 World IC Package Heat Spreaders Average Price by Region (2021-2032)
  1.3.4 Japan IC Package Heat Spreaders Production (2021-2032)
  1.3.5 China Taiwan IC Package Heat Spreaders Production (2021-2032)
  1.3.6 North America IC Package Heat Spreaders Production (2021-2032)
  1.3.7 China IC Package Heat Spreaders Production (2021-2032)
1.4 Market Drivers, Restraints and Trends
  1.4.1 IC Package Heat Spreaders Market Drivers
  1.4.2 Factors Affecting Demand
  1.4.3 IC Package Heat Spreaders Major Market Trends

2 DEMAND SUMMARY

2.1 World IC Package Heat Spreaders Demand (2021-2032)
2.2 World IC Package Heat Spreaders Consumption by Region
  2.2.1 World IC Package Heat Spreaders Consumption by Region (2021-2026)
  2.2.2 World IC Package Heat Spreaders Consumption Forecast by Region (2027-2032)
2.3 United States IC Package Heat Spreaders Consumption (2021-2032)
2.4 China IC Package Heat Spreaders Consumption (2021-2032)
2.5 Europe IC Package Heat Spreaders Consumption (2021-2032)
2.6 Japan IC Package Heat Spreaders Consumption (2021-2032)
2.7 South Korea IC Package Heat Spreaders Consumption (2021-2032)
2.8 ASEAN IC Package Heat Spreaders Consumption (2021-2032)
2.9 India IC Package Heat Spreaders Consumption (2021-2032)

3 WORLD MANUFACTURERS COMPETITIVE ANALYSIS

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3.1 World IC Package Heat Spreaders Production Value by Manufacturer (2021-2026)
3.2 World IC Package Heat Spreaders Production by Manufacturer (2021-2026)
3.3 World IC Package Heat Spreaders Average Price by Manufacturer (2021-2026)
3.4 IC Package Heat Spreaders Company Evaluation Quadrant
3.5 Industry Rank and Concentration Rate (CR)
  3.5.1 Global IC Package Heat Spreaders Industry Rank of Major Manufacturers
  3.5.2 Global Concentration Ratios (CR4) for IC Package Heat Spreaders in 2025
  3.5.3 Global Concentration Ratios (CR8) for IC Package Heat Spreaders in 2025
3.6 IC Package Heat Spreaders Market: Overall Company Footprint Analysis
  3.6.1 IC Package Heat Spreaders Market: Region Footprint
  3.6.2 IC Package Heat Spreaders Market: Company Product Type Footprint
  3.6.3 IC Package Heat Spreaders Market: Company Product Application Footprint
3.7 Competitive Environment
  3.7.1 Historical Structure of the Industry
  3.7.2 Barriers of Market Entry
  3.7.3 Factors of Competition
3.8 New Entrant and Capacity Expansion Plans
3.9 Mergers, Acquisition, Agreements, and Collaborations

4 UNITED STATES VS CHINA VS REST OF THE WORLD

4.1 United States VS China: IC Package Heat Spreaders Production Value Comparison
  4.1.1 United States VS China: IC Package Heat Spreaders Production Value Comparison (2021 & 2025 & 2032)
  4.1.2 United States VS China: IC Package Heat Spreaders Production Value Market Share Comparison (2021 & 2025 & 2032)
4.2 United States VS China: IC Package Heat Spreaders Production Comparison
  4.2.1 United States VS China: IC Package Heat Spreaders Production Comparison (2021 & 2025 & 2032)
  4.2.2 United States VS China: IC Package Heat Spreaders Production Market Share Comparison (2021 & 2025 & 2032)
4.3 United States VS China: IC Package Heat Spreaders Consumption Comparison
  4.3.1 United States VS China: IC Package Heat Spreaders Consumption Comparison (2021 & 2025 & 2032)
  4.3.2 United States VS China: IC Package Heat Spreaders Consumption Market Share Comparison (2021 & 2025 & 2032)
4.4 United States Based IC Package Heat Spreaders Manufacturers and Market Share, 2021-2026

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4.4.1 United States Based IC Package Heat Spreaders Manufacturers, Headquarters and Production Site (States, Country)
4.4.2 United States Based Manufacturers IC Package Heat Spreaders Production Value (2021-2026)
4.4.3 United States Based Manufacturers IC Package Heat Spreaders Production (2021-2026)
4.5 China Based IC Package Heat Spreaders Manufacturers and Market Share
4.5.1 China Based IC Package Heat Spreaders Manufacturers, Headquarters and Production Site (Province, Country)
4.5.2 China Based Manufacturers IC Package Heat Spreaders Production Value (2021-2026)
4.5.3 China Based Manufacturers IC Package Heat Spreaders Production (2021-2026)
4.6 Rest of World Based IC Package Heat Spreaders Manufacturers and Market Share, 2021-2026
4.6.1 Rest of World Based IC Package Heat Spreaders Manufacturers, Headquarters and Production Site (State, Country)
4.6.2 Rest of World Based Manufacturers IC Package Heat Spreaders Production Value (2021-2026)
4.6.3 Rest of World Based Manufacturers IC Package Heat Spreaders Production (2021-2026)

5 MARKET ANALYSIS BY MATERIAL

5.1 World IC Package Heat Spreaders Market Size Overview by Material: 2021 VS 2025 VS 2032
5.2 Segment Introduction by Material
5.2.1 Cu Heat Spreader
5.2.2 Stainless Steel Heat Spreader
5.3 Market Segment by Material
5.3.1 World IC Package Heat Spreaders Production by Material (2021-2032)
5.3.2 World IC Package Heat Spreaders Production Value by Material (2021-2032)
5.3.3 World IC Package Heat Spreaders Average Price by Material (2021-2032)

6 MARKET ANALYSIS BY SIZE

6.1 World IC Package Heat Spreaders Market Size Overview by Size: 2021 VS 2025 VS 2032
6.2 Segment Introduction by Size
6.2.1 Large Size (35*35mm and Above)

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6.2.2 Small Size (35*35mm Below)
6.3 Market Segment by Size
6.3.1 World IC Package Heat Spreaders Production by Size (2021-2032)
6.3.2 World IC Package Heat Spreaders Production Value by Size (2021-2032)
6.3.3 World IC Package Heat Spreaders Average Price by Size (2021-2032)

7 MARKET ANALYSIS BY TYPE

7.1 World IC Package Heat Spreaders Market Size Overview by Type: 2021 VS 2025 VS 2032
7.2 Segment Introduction by Type
7.2.1 Flip Chip Heat Spreader
7.2.2 BGA Heat Spreader
7.3 Market Segment by Type
7.3.1 World IC Package Heat Spreaders Production by Type (2021-2032)
7.3.2 World IC Package Heat Spreaders Production Value by Type (2021-2032)
7.3.3 World IC Package Heat Spreaders Average Price by Type (2021-2032)

8 MARKET ANALYSIS BY APPLICATION

8.1 World IC Package Heat Spreaders Market Size Overview by Application: 2021 VS 2025 VS 2032
8.2 Segment Introduction by Application
8.2.1 PC CPU/GPU Package
8.2.2 Server/Data Center/AI Chip Package
8.2.3 Automotive SoC/FPGA Package
8.2.4 Gaming Console
8.2.5 Others
8.3 Market Segment by Application
8.3.1 World IC Package Heat Spreaders Production by Application (2021-2032)
8.3.2 World IC Package Heat Spreaders Production Value by Application (2021-2032)
8.3.3 World IC Package Heat Spreaders Average Price by Application (2021-2032)

9 COMPANY PROFILES

9.1 Shinko
9.1.1 Shinko Details
9.1.2 Shinko Major Business
9.1.3 Shinko IC Package Heat Spreaders Product and Services

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9.1.4 Shinko IC Package Heat Spreaders Production, Price, Value, Gross Margin and Market Share (2021-2026)
9.1.5 Shinko Recent Developments/Updates
9.1.6 Shinko Competitive Strengths & Weaknesses
9.2 Honeywell Advanced Materials
9.2.1 Honeywell Advanced Materials Details
9.2.2 Honeywell Advanced Materials Major Business
9.2.3 Honeywell Advanced Materials IC Package Heat Spreaders Product and Services
9.2.4 Honeywell Advanced Materials IC Package Heat Spreaders Production, Price, Value, Gross Margin and Market Share (2021-2026)
9.2.5 Honeywell Advanced Materials Recent Developments/Updates
9.2.6 Honeywell Advanced Materials Competitive Strengths & Weaknesses
9.3 Jentech Precision Industrial
9.3.1 Jentech Precision Industrial Details
9.3.2 Jentech Precision Industrial Major Business
9.3.3 Jentech Precision Industrial IC Package Heat Spreaders Product and Services
9.3.4 Jentech Precision Industrial IC Package Heat Spreaders Production, Price, Value, Gross Margin and Market Share (2021-2026)
9.3.5 Jentech Precision Industrial Recent Developments/Updates
9.3.6 Jentech Precision Industrial Competitive Strengths & Weaknesses
9.4 I-Chiun
9.4.1 I-Chiun Details
9.4.2 I-Chiun Major Business
9.4.3 I-Chiun IC Package Heat Spreaders Product and Services
9.4.4 I-Chiun IC Package Heat Spreaders Production, Price, Value, Gross Margin and Market Share (2021-2026)
9.4.5 I-Chiun Recent Developments/Updates
9.4.6 I-Chiun Competitive Strengths & Weaknesses
9.5 Favor Precision Technology
9.5.1 Favor Precision Technology Details
9.5.2 Favor Precision Technology Major Business
9.5.3 Favor Precision Technology IC Package Heat Spreaders Product and Services
9.5.4 Favor Precision Technology IC Package Heat Spreaders Production, Price, Value, Gross Margin and Market Share (2021-2026)
9.5.5 Favor Precision Technology Recent Developments/Updates
9.5.6 Favor Precision Technology Competitive Strengths & Weaknesses
9.6 Niching Industrial Corporation
9.6.1 Niching Industrial Corporation Details

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info@marketpublishers.com

9.6.2 Niching Industrial Corporation Major Business
9.6.3 Niching Industrial Corporation IC Package Heat Spreaders Product and Services
9.6.4 Niching Industrial Corporation IC Package Heat Spreaders Production, Price, Value, Gross Margin and Market Share (2021-2026)
9.6.5 Niching Industrial Corporation Recent Developments/Updates
9.6.6 Niching Industrial Corporation Competitive Strengths & Weaknesses
9.7 Fastrong Technologies Corp.
9.7.1 Fastrong Technologies Corp. Details
9.7.2 Fastrong Technologies Corp. Major Business
9.7.3 Fastrong Technologies Corp. IC Package Heat Spreaders Product and Services
9.7.4 Fastrong Technologies Corp. IC Package Heat Spreaders Production, Price, Value, Gross Margin and Market Share (2021-2026)
9.7.5 Fastrong Technologies Corp. Recent Developments/Updates
9.7.6 Fastrong Technologies Corp. Competitive Strengths & Weaknesses
9.8 ECE (Excel Cell Electronic)
9.8.1 ECE (Excel Cell Electronic) Details
9.8.2 ECE (Excel Cell Electronic) Major Business
9.8.3 ECE (Excel Cell Electronic) IC Package Heat Spreaders Product and Services
9.8.4 ECE (Excel Cell Electronic) IC Package Heat Spreaders Production, Price, Value, Gross Margin and Market Share (2021-2026)
9.8.5 ECE (Excel Cell Electronic) Recent Developments/Updates
9.8.6 ECE (Excel Cell Electronic) Competitive Strengths & Weaknesses
9.9 Shandong Ruisi Precision Industry
9.9.1 Shandong Ruisi Precision Industry Details
9.9.2 Shandong Ruisi Precision Industry Major Business
9.9.3 Shandong Ruisi Precision Industry IC Package Heat Spreaders Product and Services
9.9.4 Shandong Ruisi Precision Industry IC Package Heat Spreaders Production, Price, Value, Gross Margin and Market Share (2021-2026)
9.9.5 Shandong Ruisi Precision Industry Recent Developments/Updates
9.9.6 Shandong Ruisi Precision Industry Competitive Strengths & Weaknesses
9.10 HongRiDa Electronics (HRD)
9.10.1 HongRiDa Electronics (HRD) Details
9.10.2 HongRiDa Electronics (HRD) Major Business
9.10.3 HongRiDa Electronics (HRD) IC Package Heat Spreaders Product and Services
9.10.4 HongRiDa Electronics (HRD) IC Package Heat Spreaders Production, Price, Value, Gross Margin and Market Share (2021-2026)
9.10.5 HongRiDa Electronics (HRD) Recent Developments/Updates

+357 96 030922
info@marketpublishers.com

9.10.6 HongRiDa Electronics (HRD) Competitive Strengths & Weaknesses
9.11 TBT Co., Ltd
9.11.1 TBT Co., Ltd Details
9.11.2 TBT Co., Ltd Major Business
9.11.3 TBT Co., Ltd IC Package Heat Spreaders Product and Services
9.11.4 TBT Co., Ltd IC Package Heat Spreaders Production, Price, Value, Gross Margin and Market Share (2021-2026)
9.11.5 TBT Co., Ltd Recent Developments/Updates
9.11.6 TBT Co., Ltd Competitive Strengths & Weaknesses
9.12 Ningbo S J Electronics
9.12.1 Ningbo S J Electronics Details
9.12.2 Ningbo S J Electronics Major Business
9.12.3 Ningbo S J Electronics IC Package Heat Spreaders Product and Services
9.12.4 Ningbo S J Electronics IC Package Heat Spreaders Production, Price, Value, Gross Margin and Market Share (2021-2026)
9.12.5 Ningbo S J Electronics Recent Developments/Updates
9.12.6 Ningbo S J Electronics Competitive Strengths & Weaknesses

10 INDUSTRY CHAIN ANALYSIS

10.1 IC Package Heat Spreaders Industry Chain
10.2 IC Package Heat Spreaders Upstream Analysis
10.2.1 IC Package Heat Spreaders Core Raw Materials
10.2.2 Main Manufacturers of IC Package Heat Spreaders Core Raw Materials
10.3 Midstream Analysis
10.4 Downstream Analysis
10.5 IC Package Heat Spreaders Production Mode
10.6 IC Package Heat Spreaders Procurement Model
10.7 IC Package Heat Spreaders Industry Sales Model and Sales Channels
10.7.1 IC Package Heat Spreaders Sales Model
10.7.2 IC Package Heat Spreaders Typical Distributors

11 RESEARCH FINDINGS AND CONCLUSION

12 APPENDIX

12.1 Methodology
12.2 Research Process and Data Source
12.3 Disclaimer

+357 96 030922
info@marketpublishers.com

List Of Tables

LIST OF TABLES

Table 1. World IC Package Heat Spreaders Production Value by Region (2021, 2025 and 2032) & (USD Million)
Table 2. World IC Package Heat Spreaders Production Value by Region (2021-2026) & (USD Million)
Table 3. World IC Package Heat Spreaders Production Value by Region (2027-2032) & (USD Million)
Table 4. World IC Package Heat Spreaders Production Value Market Share by Region (2021-2026)
Table 5. World IC Package Heat Spreaders Production Value Market Share by Region (2027-2032)
Table 6. World IC Package Heat Spreaders Production by Region (2021-2026) & (Million Pcs)
Table 7. World IC Package Heat Spreaders Production by Region (2027-2032) & (Million Pcs)
Table 8. World IC Package Heat Spreaders Production Market Share by Region (2021-2026)
Table 9. World IC Package Heat Spreaders Production Market Share by Region (2027-2032)
Table 10. World IC Package Heat Spreaders Average Price by Region (2021-2026) & (US$/Pcs)
Table 11. World IC Package Heat Spreaders Average Price by Region (2027-2032) & (US$/Pcs)
Table 12. IC Package Heat Spreaders Major Market Trends
Table 13. World IC Package Heat Spreaders Consumption Growth Rate Forecast by Region (2021 & 2025 & 2032) & (Million Pcs)
Table 14. World IC Package Heat Spreaders Consumption by Region (2021-2026) & (Million Pcs)
Table 15. World IC Package Heat Spreaders Consumption Forecast by Region (2027-2032) & (Million Pcs)
Table 16. World IC Package Heat Spreaders Production Value by Manufacturer (2021-2026) & (USD Million)
Table 17. Production Value Market Share of Key IC Package Heat Spreaders Producers in 2025
Table 18. World IC Package Heat Spreaders Production by Manufacturer (2021-2026) & (Million Pcs)

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info@marketpublishers.com

Table 19. Production Market Share of Key IC Package Heat Spreaders Producers in 2025
Table 20. World IC Package Heat Spreaders Average Price by Manufacturer (2021-2026) & (US$/Pcs)
Table 21. Global IC Package Heat Spreaders Company Evaluation Quadrant
Table 22. World IC Package Heat Spreaders Industry Rank of Major Manufacturers, Based on Production Value in 2025
Table 23. Head Office and IC Package Heat Spreaders Production Site of Key Manufacturer
Table 24. IC Package Heat Spreaders Market: Company Product Type Footprint
Table 25. IC Package Heat Spreaders Market: Company Product Application Footprint
Table 26. IC Package Heat Spreaders Competitive Factors
Table 27. IC Package Heat Spreaders New Entrant and Capacity Expansion Plans
Table 28. IC Package Heat Spreaders Mergers & Acquisitions Activity
Table 29. United States VS China IC Package Heat Spreaders Production Value Comparison, (2021 & 2025 & 2032) & (USD Million)
Table 30. United States VS China IC Package Heat Spreaders Production Comparison, (2021 & 2025 & 2032) & (Million Pcs)
Table 31. United States VS China IC Package Heat Spreaders Consumption Comparison, (2021 & 2025 & 2032) & (Million Pcs)
Table 32. United States Based IC Package Heat Spreaders Manufacturers, Headquarters and Production Site (States, Country)
Table 33. United States Based Manufacturers IC Package Heat Spreaders Production Value, (2021-2026) & (USD Million)
Table 34. United States Based Manufacturers IC Package Heat Spreaders Production Value Market Share (2021-2026)
Table 35. United States Based Manufacturers IC Package Heat Spreaders Production (2021-2026) & (Million Pcs)
Table 36. United States Based Manufacturers IC Package Heat Spreaders Production Market Share (2021-2026)
Table 37. China Based IC Package Heat Spreaders Manufacturers, Headquarters and Production Site (Province, Country)
Table 38. China Based Manufacturers IC Package Heat Spreaders Production Value, (2021-2026) & (USD Million)
Table 39. China Based Manufacturers IC Package Heat Spreaders Production Value Market Share (2021-2026)
Table 40. China Based Manufacturers IC Package Heat Spreaders Production, (2021-2026) & (Million Pcs)
Table 41. China Based Manufacturers IC Package Heat Spreaders Production Market

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Share (2021-2026)
Table 42. Rest of World Based IC Package Heat Spreaders Manufacturers, Headquarters and Production Site (State, Country)
Table 43. Rest of World Based Manufacturers IC Package Heat Spreaders Production Value, (2021-2026) & (USD Million)
Table 44. Rest of World Based Manufacturers IC Package Heat Spreaders Production Value Market Share (2021-2026)
Table 45. Rest of World Based Manufacturers IC Package Heat Spreaders Production, (2021-2026) & (Million Pcs)
Table 46. Rest of World Based Manufacturers IC Package Heat Spreaders Production Market Share (2021-2026)
Table 47. World IC Package Heat Spreaders Production Value by Material, (USD Million), 2021 & 2025 & 2032
Table 48. World IC Package Heat Spreaders Production by Material (2021-2026) & (Million Pcs)
Table 49. World IC Package Heat Spreaders Production by Material (2027-2032) & (Million Pcs)
Table 50. World IC Package Heat Spreaders Production Value by Material (2021-2026) & (USD Million)
Table 51. World IC Package Heat Spreaders Production Value by Material (2027-2032) & (USD Million)
Table 52. World IC Package Heat Spreaders Average Price by Material (2021-2026) & (US$/Pcs)
Table 53. World IC Package Heat Spreaders Average Price by Material (2027-2032) & (US$/Pcs)
Table 54. World IC Package Heat Spreaders Production Value by Size, (USD Million), 2021 & 2025 & 2032
Table 55. World IC Package Heat Spreaders Production by Size (2021-2026) & (Million Pcs)
Table 56. World IC Package Heat Spreaders Production by Size (2027-2032) & (Million Pcs)
Table 57. World IC Package Heat Spreaders Production Value by Size (2021-2026) & (USD Million)
Table 58. World IC Package Heat Spreaders Production Value by Size (2027-2032) & (USD Million)
Table 59. World IC Package Heat Spreaders Average Price by Size (2021-2026) & (US$/Pcs)
Table 60. World IC Package Heat Spreaders Average Price by Size (2027-2032) & (US$/Pcs)

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Table 61. World IC Package Heat Spreaders Production Value by Type, (USD Million), 2021 & 2025 & 2032
Table 62. World IC Package Heat Spreaders Production by Type (2021-2026) & (Million Pcs)
Table 63. World IC Package Heat Spreaders Production by Type (2027-2032) & (Million Pcs)
Table 64. World IC Package Heat Spreaders Production Value by Type (2021-2026) & (USD Million)
Table 65. World IC Package Heat Spreaders Production Value by Type (2027-2032) & (USD Million)
Table 66. World IC Package Heat Spreaders Average Price by Type (2021-2026) & (US$/Pcs)
Table 67. World IC Package Heat Spreaders Average Price by Type (2027-2032) & (US$/Pcs)
Table 68. World IC Package Heat Spreaders Production Value by Application, (USD Million), 2021 & 2025 & 2032
Table 69. World IC Package Heat Spreaders Production by Application (2021-2026) & (Million Pcs)
Table 70. World IC Package Heat Spreaders Production by Application (2027-2032) & (Million Pcs)
Table 71. World IC Package Heat Spreaders Production Value by Application (2021-2026) & (USD Million)
Table 72. World IC Package Heat Spreaders Production Value by Application (2027-2032) & (USD Million)
Table 73. World IC Package Heat Spreaders Average Price by Application (2021-2026) & (US$/Pcs)
Table 74. World IC Package Heat Spreaders Average Price by Application (2027-2032) & (US$/Pcs)
Table 75. Shinko Basic Information, Manufacturing Base and Competitors
Table 76. Shinko Major Business
Table 77. Shinko IC Package Heat Spreaders Product and Services
Table 78. Shinko IC Package Heat Spreaders Production (Million Pcs), Price (US$/Pcs), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 79. Shinko Recent Developments/Updates
Table 80. Shinko Competitive Strengths & Weaknesses
Table 81. Honeywell Advanced Materials Basic Information, Manufacturing Base and Competitors
Table 82. Honeywell Advanced Materials Major Business
Table 83. Honeywell Advanced Materials IC Package Heat Spreaders Product and

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Services
Table 84. Honeywell Advanced Materials IC Package Heat Spreaders Production (Million Pcs), Price (US$/Pcs), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 85. Honeywell Advanced Materials Recent Developments/Updates
Table 86. Honeywell Advanced Materials Competitive Strengths & Weaknesses
Table 87. Jentech Precision Industrial Basic Information, Manufacturing Base and Competitors
Table 88. Jentech Precision Industrial Major Business
Table 89. Jentech Precision Industrial IC Package Heat Spreaders Product and Services
Table 90. Jentech Precision Industrial IC Package Heat Spreaders Production (Million Pcs), Price (US$/Pcs), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 91. Jentech Precision Industrial Recent Developments/Updates
Table 92. Jentech Precision Industrial Competitive Strengths & Weaknesses
Table 93. I-Chiun Basic Information, Manufacturing Base and Competitors
Table 94. I-Chiun Major Business
Table 95. I-Chiun IC Package Heat Spreaders Product and Services
Table 96. I-Chiun IC Package Heat Spreaders Production (Million Pcs), Price (US$/Pcs), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 97. I-Chiun Recent Developments/Updates
Table 98. I-Chiun Competitive Strengths & Weaknesses
Table 99. Favor Precision Technology Basic Information, Manufacturing Base and Competitors
Table 100. Favor Precision Technology Major Business
Table 101. Favor Precision Technology IC Package Heat Spreaders Product and Services
Table 102. Favor Precision Technology IC Package Heat Spreaders Production (Million Pcs), Price (US$/Pcs), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 103. Favor Precision Technology Recent Developments/Updates
Table 104. Favor Precision Technology Competitive Strengths & Weaknesses
Table 105. Niching Industrial Corporation Basic Information, Manufacturing Base and Competitors
Table 106. Niching Industrial Corporation Major Business
Table 107. Niching Industrial Corporation IC Package Heat Spreaders Product and Services

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Table 108. Niching Industrial Corporation IC Package Heat Spreaders Production (Million Pcs), Price (US$/Pcs), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 109. Niching Industrial Corporation Recent Developments/Updates
Table 110. Niching Industrial Corporation Competitive Strengths & Weaknesses
Table 111. Fastrong Technologies Corp. Basic Information, Manufacturing Base and Competitors
Table 112. Fastrong Technologies Corp. Major Business
Table 113. Fastrong Technologies Corp. IC Package Heat Spreaders Product and Services
Table 114. Fastrong Technologies Corp. IC Package Heat Spreaders Production (Million Pcs), Price (US$/Pcs), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 115. Fastrong Technologies Corp. Recent Developments/Updates
Table 116. Fastrong Technologies Corp. Competitive Strengths & Weaknesses
Table 117. ECE (Excel Cell Electronic) Basic Information, Manufacturing Base and Competitors
Table 118. ECE (Excel Cell Electronic) Major Business
Table 119. ECE (Excel Cell Electronic) IC Package Heat Spreaders Product and Services
Table 120. ECE (Excel Cell Electronic) IC Package Heat Spreaders Production (Million Pcs), Price (US$/Pcs), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 121. ECE (Excel Cell Electronic) Recent Developments/Updates
Table 122. ECE (Excel Cell Electronic) Competitive Strengths & Weaknesses
Table 123. Shandong Ruisi Precision Industry Basic Information, Manufacturing Base and Competitors
Table 124. Shandong Ruisi Precision Industry Major Business
Table 125. Shandong Ruisi Precision Industry IC Package Heat Spreaders Product and Services
Table 126. Shandong Ruisi Precision Industry IC Package Heat Spreaders Production (Million Pcs), Price (US$/Pcs), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 127. Shandong Ruisi Precision Industry Recent Developments/Updates
Table 128. Shandong Ruisi Precision Industry Competitive Strengths & Weaknesses
Table 129. HongRiDa Electronics (HRD) Basic Information, Manufacturing Base and Competitors
Table 130. HongRiDa Electronics (HRD) Major Business
Table 131. HongRiDa Electronics (HRD) IC Package Heat Spreaders Product and

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Services
Table 132. HongRiDa Electronics (HRD) IC Package Heat Spreaders Production (Million Pcs), Price (US$/Pcs), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 133. HongRiDa Electronics (HRD) Recent Developments/Updates
Table 134. HongRiDa Electronics (HRD) Competitive Strengths & Weaknesses
Table 135. TBT Co., Ltd Basic Information, Manufacturing Base and Competitors
Table 136. TBT Co., Ltd Major Business
Table 137. TBT Co., Ltd IC Package Heat Spreaders Product and Services
Table 138. TBT Co., Ltd IC Package Heat Spreaders Production (Million Pcs), Price (US$/Pcs), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 139. TBT Co., Ltd Recent Developments/Updates
Table 140. TBT Co., Ltd Competitive Strengths & Weaknesses
Table 141. Ningbo S J Electronics Basic Information, Manufacturing Base and Competitors
Table 142. Ningbo S J Electronics Major Business
Table 143. Ningbo S J Electronics IC Package Heat Spreaders Product and Services
Table 144. Ningbo S J Electronics IC Package Heat Spreaders Production (Million Pcs), Price (US$/Pcs), Production Value (USD Million), Gross Margin and Market Share (2021-2026)
Table 145. Ningbo S J Electronics Recent Developments/Updates
Table 146. Ningbo S J Electronics Competitive Strengths & Weaknesses
Table 147. Global Key Players of IC Package Heat Spreaders Upstream (Raw Materials)
Table 148. Global IC Package Heat Spreaders Typical Customers
Table 149. IC Package Heat Spreaders Typical Distributors

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List Of Figures

LIST OF FIGURES

Figure 1. IC Package Heat Spreaders Picture
Figure 2. World IC Package Heat Spreaders Production Value: 2021 & 2025 & 2032, (USD Million)
Figure 3. World IC Package Heat Spreaders Production Value and Forecast (2021-2032) & (USD Million)
Figure 4. World IC Package Heat Spreaders Production (2021-2032) & (Million Pcs)
Figure 5. World IC Package Heat Spreaders Average Price (2021-2032) & (US$/Pcs)
Figure 6. World IC Package Heat Spreaders Production Value Market Share by Region (2021-2032)
Figure 7. World IC Package Heat Spreaders Production Market Share by Region (2021-2032)
Figure 8. Japan IC Package Heat Spreaders Production (2021-2032) & (Million Pcs)
Figure 9. China Taiwan IC Package Heat Spreaders Production (2021-2032) & (Million Pcs)
Figure 10. North America IC Package Heat Spreaders Production (2021-2032) & (Million Pcs)
Figure 11. China IC Package Heat Spreaders Production (2021-2032) & (Million Pcs)
Figure 12. IC Package Heat Spreaders Market Drivers
Figure 13. Factors Affecting Demand
Figure 14. World IC Package Heat Spreaders Consumption (2021-2032) & (Million Pcs)
Figure 15. World IC Package Heat Spreaders Consumption Market Share by Region (2021-2032)
Figure 16. United States IC Package Heat Spreaders Consumption (2021-2032) & (Million Pcs)
Figure 17. China IC Package Heat Spreaders Consumption (2021-2032) & (Million Pcs)
Figure 18. Europe IC Package Heat Spreaders Consumption (2021-2032) & (Million Pcs)
Figure 19. Japan IC Package Heat Spreaders Consumption (2021-2032) & (Million Pcs)
Figure 20. South Korea IC Package Heat Spreaders Consumption (2021-2032) & (Million Pcs)
Figure 21. ASEAN IC Package Heat Spreaders Consumption (2021-2032) & (Million Pcs)
Figure 22. India IC Package Heat Spreaders Consumption (2021-2032) & (Million Pcs)
Figure 23. Producer Shipments of IC Package Heat Spreaders by Manufacturer Revenue ($MM) and Market Share (%): 2025

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Figure 24. Global Four-firm Concentration Ratios (CR4) for IC Package Heat Spreaders Markets in 2025
Figure 25. Global Four-firm Concentration Ratios (CR8) for IC Package Heat Spreaders Markets in 2025
Figure 26. United States VS China: IC Package Heat Spreaders Production Value Market Share Comparison (2021 & 2025 & 2032)
Figure 27. United States VS China: IC Package Heat Spreaders Production Market Share Comparison (2021 & 2025 & 2032)
Figure 28. United States VS China: IC Package Heat Spreaders Consumption Market Share Comparison (2021 & 2025 & 2032)
Figure 29. United States Based Manufacturers IC Package Heat Spreaders Production Market Share 2025
Figure 30. China Based Manufacturers IC Package Heat Spreaders Production Market Share 2025
Figure 31. Rest of World Based Manufacturers IC Package Heat Spreaders Production Market Share 2025
Figure 32. World IC Package Heat Spreaders Production Value by Material, (USD Million), 2021 & 2025 & 2032
Figure 33. World IC Package Heat Spreaders Production Value Market Share by Material in 2025
Figure 34. Cu Heat Spreader
Figure 35. Stainless Steel Heat Spreader
Figure 36. World IC Package Heat Spreaders Production Market Share by Material (2021-2032)
Figure 37. World IC Package Heat Spreaders Production Value Market Share by Material (2021-2032)
Figure 38. World IC Package Heat Spreaders Average Price by Material (2021-2032) & (US$/Pcs)
Figure 39. World IC Package Heat Spreaders Production Value by Size, (USD Million), 2021 & 2025 & 2032
Figure 40. World IC Package Heat Spreaders Production Value Market Share by Size in 2025
Figure 41. Large Size (35*35mm and Above)
Figure 42. Small Size (35*35mm Below)
Figure 43. World IC Package Heat Spreaders Production Market Share by Size (2021-2032)
Figure 44. World IC Package Heat Spreaders Production Value Market Share by Size (2021-2032)
Figure 45. World IC Package Heat Spreaders Average Price by Size (2021-2032) &

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(US$/Pcs)
Figure 46. World IC Package Heat Spreaders Production Value by Type, (USD Million), 2021 & 2025 & 2032
Figure 47. World IC Package Heat Spreaders Production Value Market Share by Type in 2025
Figure 48. Flip Chip Heat Spreader
Figure 49. BGA Heat Spreader
Figure 50. World IC Package Heat Spreaders Production Market Share by Type (2021-2032)
Figure 51. World IC Package Heat Spreaders Production Value Market Share by Type (2021-2032)
Figure 52. World IC Package Heat Spreaders Average Price by Type (2021-2032) & (US$/Pcs)
Figure 53. World IC Package Heat Spreaders Production Value by Application, (USD Million), 2021 & 2025 & 2032
Figure 54. World IC Package Heat Spreaders Production Value Market Share by Application in 2025
Figure 55. PC CPU/GPU Package
Figure 56. Server/Data Center/AI Chip Package
Figure 57. Automotive SoC/FPGA Package
Figure 58. Gaming Console
Figure 59. Others
Figure 60. World IC Package Heat Spreaders Production Market Share by Application (2021-2032)
Figure 61. World IC Package Heat Spreaders Production Value Market Share by Application (2021-2032)
Figure 62. World IC Package Heat Spreaders Average Price by Application (2021-2032) & (US$/Pcs)
Figure 63. IC Package Heat Spreaders Industry Chain
Figure 64. IC Package Heat Spreaders Procurement Model
Figure 65. IC Package Heat Spreaders Sales Model
Figure 66. IC Package Heat Spreaders Sales Channels, Direct Sales, and Distribution
Figure 67. Methodology
Figure 68. Research Process and Data Source

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